

Title (en)

ACRYLATED OLIGOMER/THERMOPLASTIC POLYAMIDE PRESIZE COATINGS FOR ABRASIVE ARTICLE BACKINGS

Title (de)

BESCHICHTUNGEN AUS ACRYLIERTEN OLIGOMEREN UND THERMOPLASTISCHEM POLYAMID FÜR HINTERLEGUNGEN VON SCHLEIFARTIKELN

Title (fr)

ENDUITS DE PRE-ENCOLLAGE EN POLYAMIDE THERMOPLASTIQUE/OLIGOMERE ACRYLE POUR SUPPORTS DORSAUX D'ARTICLES ABRASIFS

Publication

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Application

**EP 99960250 A 19991109**

Priority

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Abstract (en)

[origin: WO0037569A1] The present invention provides a composition for use in coated abrasives. The curable composition comprises a mixture of: i) from about 25 to about 75 weight percent of acrylated oligomer; ii) from about 75 to about 25 weight percent of a thermoplastic polyamide miscible in said acrylated oligomer, the weight percents being based on the total resin content; and iii) a sufficient amount of a catalyst for the curable acrylated oligomer, said catalyst being stable at a temperature of mixing of the components. The present invention also provides single and multilayered treated backing substrates for use in coated abrasives.

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IPC 8 full level

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